



Title of Change:	Qualification 4inch Chip Tray Raw Material from PBT to MPPO and inner pocket modification at KINGPAK.							
Effective date:	30 May 2019							
Contact information:	Contact your local ON Semiconductor Sales Office or <sophia.kuo@onsemi.com>							
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.							
Change Category:	<input type="checkbox"/> Wafer Fab <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input checked="" type="checkbox"/> Other <u>CSP chip tray material change and inner pocket redesign</u>							
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input checked="" type="checkbox"/> Other: <u>CSP chip tray raw material change and inner pocket redesign</u>							
Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: KINGPAK						
Description and Purpose:								
There is no changes to outer dimension, marking rule and only modify inner pocket and change raw material for CSP unit lay down safely during process and shipment.								
	<table border="1"> <thead> <tr> <th></th> <th>Before Change Description</th> <th>After Change Description</th> </tr> </thead> <tbody> <tr> <td>Other Changes</td> <td>CSP chip tray with PBT, original raw material</td> <td>CSP chip tray with MPPO new raw material and inner pocket modification without outer dimension or size changes.</td> </tr> </tbody> </table>			Before Change Description	After Change Description	Other Changes	CSP chip tray with PBT, original raw material	CSP chip tray with MPPO new raw material and inner pocket modification without outer dimension or size changes.
	Before Change Description	After Change Description						
Other Changes	CSP chip tray with PBT, original raw material	CSP chip tray with MPPO new raw material and inner pocket modification without outer dimension or size changes.						
List of Affected Parts:								
<p>Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.</p> <p>AR1335CSSC11SMKA0-CP1 AR1335CSSC11SMKA0-CP2 AR1335CSSC11SMKA0-CR AR1335CSSC11SMKA0-CR1</p>								



Appendix A: Changed Products

Product	Customer Part Number
AR1335CSSC11SMKA0-CP1	
AR1335CSSC11SMKA0-CP2	
AR1335CSSC11SMKA0-CR	
AR1335CSSC11SMKA0-CR1	